

# Willkommen bei O-Leading

O-Leading ist bestrebt, Ihr One-Stop-Lösungspartner in der EMS-Lieferkette zu sein, einschließlich Leiterplattendesign, Leiterplattenherstellung und Leiterplattenbestückung (PCB Assembly, PCBA) Wir können vom schnellen Drehungsprototyp zur mittleren u. Massenproduktion stützen.

Im Allgemeinen sind unsere globalen Kunden von unseren Dienstleistungen sehr beeindruckt: Schnelle Reaktion, wettbewerbsfähiger Preis und Qualitätsverpflichtung. Die Bereitstellung von mehr wertvollem technischen Service und Gesamtlösung ist der Weg, der O nach vorne weist.

Mit Blick auf die Zukunft wird sich O-Lead wie immer auf die Innovation und Entwicklung der Technologie für die Elektronikfertigung konzentrieren und beharrliche Anstrengungen unternehmen, um erstklassige Dienstleistungen aus einer Hand für PCB und PCBA zu erbringen und mehr Wert für unsere Kunden zu schaffen.

BITTE KLICKEN SIE HIER FÜR WEITERE INFORMATIONEN: [Produktion von gedruckten Schaltungen](#)

## Produktbeschreibung

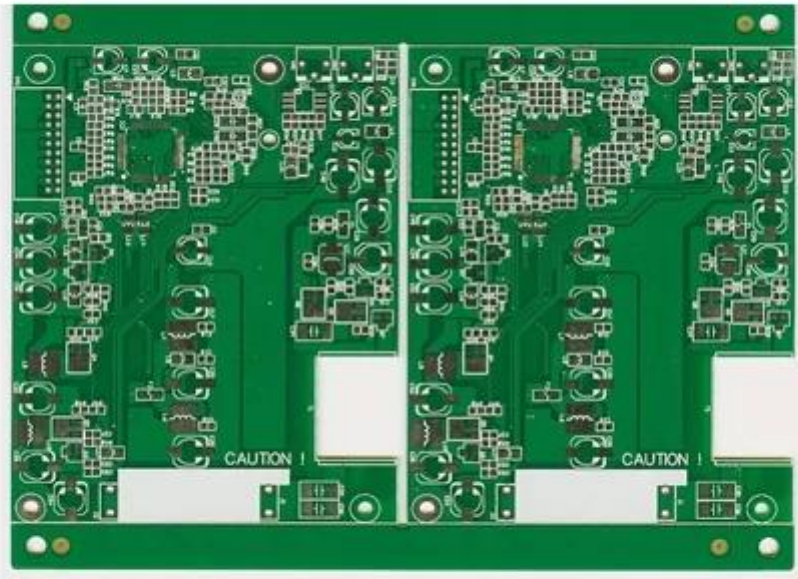
Herkunftsort	Guangdong China (Festland)	Markenname	O-Führer
Grundmaterial	FR-4, Aluminium	Dicke von Kupfer	0,5 Unzen - 5 Unzen
Mindest. Größe des Lochs	0,2 mm	Mindest. Breite der Linie	0,2 mm
Oberflächenfinish	Goldimmersion, OSP, bleifreies HASL	Dicke des Tisches	0,1-5 mm
Anwendbar auf	LED, Handy, Klimaanlage, Waschmaschinen	Charakter	Industriesteuerungsplatine
zertifiziert	ISO9001, UL, RoHS, SGS	Q / CTN	10PCS-100PCS
Gewicht	0,01 kg -5 kg	MOQ	10 Stück
Modellnummer	pcbba hersteller pcb montage energienbank	Mindest. Zeilenabstand	0,2 mm
Farbe	blau, rot, grün, schwarz, gelb	Preis	\$ 0.1- \$ 10
tippe desigh	Anforderung des Kunden	Schneide es	0,01 m3 bis 10 m3

### Produktbeschreibung

### Professionelle Herstellung von Leiterplatten seit 16 Jahren

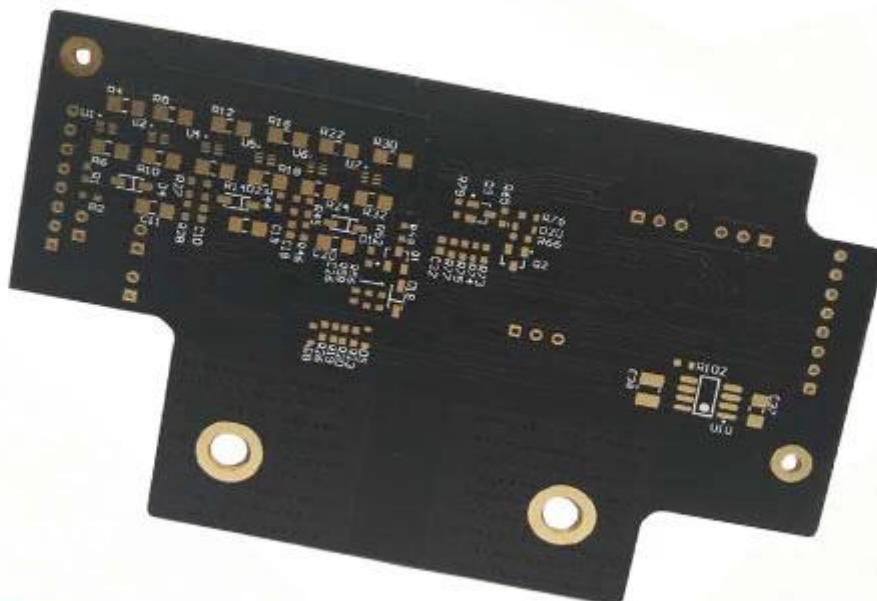
Artikel	2014		2015 ~ 2016		2017 ~ 2018	
	Volumen	Stichprobe	Volumen	Stichprobe	Volumen	Stichprobe
Level zählen	32	42	38	44	42	48
Linie / Abstand min (µm)	50/50	40/45	40/45	40/40	35/40	35/35
Mindestloch Durchmesser (mm)	00:15	00:10	00:15	00:10	00:15	00:10

Proportionen von PTH	14: 1	16: 1	16: 1	18: 1	18: 1	20: 1
N + C + N	4 + C + 4	5 + C + 5	5 + C + 5	6 + C + 6	5 + C + 5	6 + C + 6
Beliebige Ebenenverschaltung	5 + 2 + 5	6 + 2 + 6	5 + 2 + 5	6 + 2 + 6	5 + 2 + 5	6 + 2 + 6
Platte weg füllen	JEP	-	JEP	-	JEP	-
Mindest. Kerndicke (ohne Kupfer) (µm)	50	40	40	30	40	30
Mindest. Laserbohrerdurchmesser (µm)	75	65	65	50	50	40
Weit oben begraben Loch / weg gestapelt	JEP	-	JEP	-	JEP	-
Material	FR4, Megtron, Nelco, Rogers, schweres Kupfer usw.					
Eingebaute Kondensatorplatine	JEP	-	JEP	-	JEP	-
Oberflächenprozess	Bleifreies HASL, ENIG, OSP, Silber durch Eintauchen, Eintauchteich, Gold flash, vergoldung, selektive hartvergoldung, Abziehbare Schweißmaske, Carbon-Tinte					

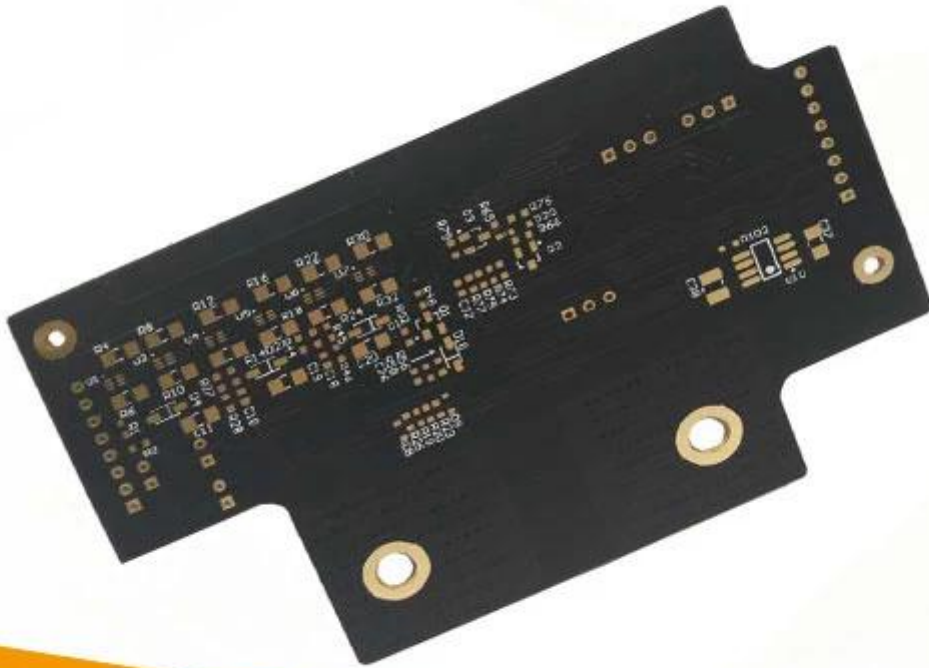


[www.o-leading.com](http://www.o-leading.com)

**Prototypenhersteller Pcb China**



[www.o-leading.com](http://www.o-leading.com)



[www.o-leading.com](http://www.o-leading.com)

[Hersteller von Leiterplatten](#)

Unser Team





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Factory PCB

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Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

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Factory SMT

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# Zertifizierungen

CICC INSPECTION CERTIFICATION



**嘉泰认证**

**QUALITY MANAGEMENT SYSTEM CERTIFICATE**  
Certificate No: 18118Q10347R05

**We hereby certify that**  
**O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED**  
Credit No: 61691591-000-07-18-7  
Registration Add: FLAT/RM 1205 12/F TAI SANG BANK BUILDING 130-132 DES VODEUS ROAD CENTRAL HK  
Business Add: 1213, Floor 13, Fortune Building, Danshui Town, Huiyang District, Huizhou, Guangdong, China

Has implemented and maintains a **Quality Management System** Which fulfills the requirements of the following standards  
GB/T19001-2016 idt ISO9001:2015

**Scope of certification**  
Sales of printed circuit boards

Initial issuance period: February 27, 2018  
Renewal date: April 22, 2019  
This certificate is valid during: April 22, 2019 – February 26, 2021  
This certificate is invalid without CICC qualified label in the following period

First supervision and audit	Second supervision and audit	Qualified mark
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The certification registration number does not include those production stages which fail to be covered by the relevant effective administrative procedures and qualification procedures stipulated by the state. The effectiveness of this certificate shall be restricted to those activities which are covered by the certification. The actual information of this certification can be searched on the internet of CICC www.cicc.com.cn






CICC INSPECTION CERTIFICATION



**嘉泰认证**

**质量管理体系认证证书**  
证书号: 18118Q10347R05

**兹证明**  
**诚领供应链（香港）有限公司**  
统一社会信用代码: 61691591-000-07-18-7  
注册地址: 香港中環德輔道中 130-132 號大生銀行大廈 1205 室  
经营地址: 广东惠州惠阳淡水南亨西路财富大厦 13 楼 1313

**建立的质量管理体系符合**  
GB/T19001-2016 idt ISO9001:2015 质量标准适用条款的要求

**认证范围**  
印刷线路板的销售

初次获证日期: 2018年02月27日  
换证日期: 2019年04月22日  
证书有效期: 自2019年04月22日至2021年02月26日  
在下列期限内, 未经 CICC 黏贴合格标贴, 本证书无效

第一次监督	第二次监督	黏贴处
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Test Report

No. SZXEC1900530401 Date: 30 Mar 2019 Page 1 of 6

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313.FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ
Date of Sample Received : 22 Mar 2019
Testing Period : 22 Mar 2019 - 30 Mar 2019
Test Requested : Selected test(s) as requested by client.
Test Method : Please refer to next page(s).
Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina
Tina Fan
Approved Signatory



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Test Report

No. SZXEC1900530401 Date: 30 Mar 2019 Page 2 of 6

Test Results :

Test Part Description :

Table with 3 columns: Specimen No., SGS Sample ID, Description. Row 1: SN1, SZX19-005304.001, Green"PCB"

Remarks :

- (1) 1 mg/kg = 1 ppm = 0.0001%
(2) MDL = Method Detection Limit
(3) ND = Not Detected (< MDL)
(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Table with 5 columns: Test Item(s), Limit, Unit, MDL, QZT. Lists various heavy metals and phthalates with their respective limits and units.



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## ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

## Wiring, Printed - Component

See General Information for Wiring, Printed - Component

**O-LEADING SUPPLY CHAIN (HK) CO LTD**

E490354

ROOM 1205, 12/F  
TAI SANG BANK BLDG  
130-132 DES VOEUS ROAD  
CENTRAL, HONG KONG

Type	Cond Width		Cond Thk mic(mil)	SS/ DS/ DSO	Max	Max		Meets UL796	C		
	Min	Edge			Area Diam	Solder Limits	Oper Temp			Flame	
	mm(in)	mm(in)			mm(in)	C	sec	C	Class	DSR	I
<b>Multilayer (mass laminate) printed wiring boards.</b>											
<b>O-LEADING-401</b>	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
<b>O-LEADING-407</b>	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
<b>Multilayer printed wiring boards.</b>											
<b>O-LEADING-408</b>	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
<b>Single layer printed wiring boards.</b>											
<b>O-LEADING-002</b>	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
<b>O-LEADING-003</b>	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
<b>O-LEADING-033</b>	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
<b>O-LEADING-205</b>	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
<b>O-LEADING-206</b>	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
<b>O-LEADING-D01</b>	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
<b>O-LEADING-S01</b>	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

## WIRING, PRINTED - COMPONENT | UL Product iQ

<b>O-LEADING-S02</b>	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲	*
<b>O-LEADING-S03</b>	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

\* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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## Shipping service



Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days

## Prozessfähigkeit

### PCB-Produktionsmöglichkeiten

Schicht Anzahl: 1Layer-32Layer

Fertige Kupferdicke: 1 / 3oz-12oz

Min. Linienbreite / interner Abstand: 3,0 mil / 3,0 mil

Min. Linienbreite / Abstand extern: 4.0mil / 4.0mil

Maximales Seitenverhältnis: 10: 1

Brettstärke: 0.2mm-5.0mm

Max Panel Größe (Zoll): 635 \* 1500 mm

Mindestbohrlochgröße: 4mil

Plated Hole Tolerance: +/- 3mil

Blind / Buried Vias (All-Typen): JA

Via Fill (leitend, nicht leitend): JA

Basismaterial: FR-4, FR-4high Tg. Halogenfreies Material, Rogers, Aluminiumbasis,Polyimid,  
Schweres Kupfer

Oberflächen: HASL, OSP, ENIG, HAL-LF, Versilberung,Immersiondose, Goldfinger, Carbon-Tinte

### SMT-Produktionsmöglichkeiten

Leiterplattenmaterial: FR-4, CEM-1, CEM-3, Leiterplatte auf Aluminiumbasis  
Maximale Leiterplattengröße: 510 x 460 mm  
Min PCB Größe: 50x50mm  
PWB-Stärke: 0.5mm-4.5mm  
Brettstärke: 0.5-4mm  
Min. Komponentengröße: 0201  
Komponente mit Standardchipgröße: 0603 und größer  
Maximale Höhe der Komponente: 15 mm  
Min. Steigung: 0,3 mm  
Min. BGA-Kugelpitch: 0,4 mm  
Platzierungsgenauigkeit: +/- 0,03 mm